

# Converter - Brake - Inverter Module

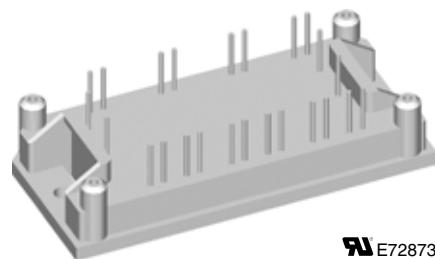
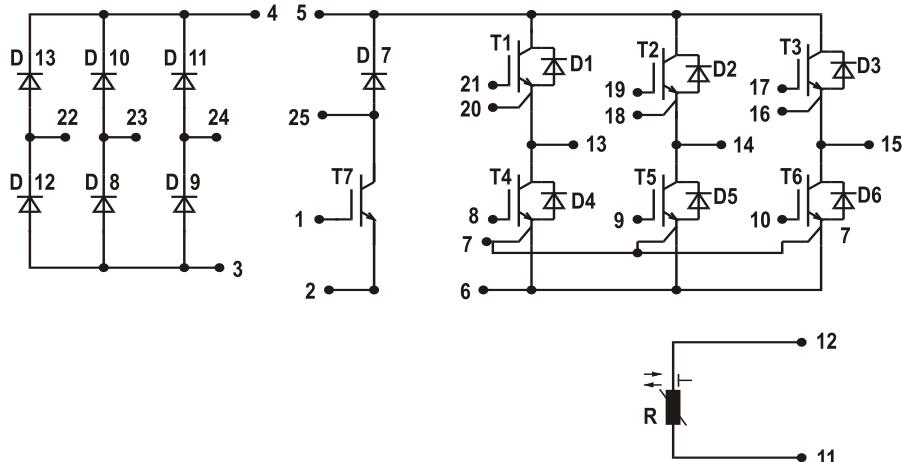
## XPT IGBT

Preliminary data

Three Phase Rectifier	Brake Chopper	Three Phase Inverter
$V_{RRM} = 1600 \text{ V}$	$V_{CES} = 1200 \text{ V}$	$V_{CES} = 1200 \text{ V}$
$I_{DAVM25} = 100 \text{ A}$	$I_{C25} = 17 \text{ A}$	$I_{C25} = 17 \text{ A}$
$I_{FSM} = 320 \text{ A}$	$V_{CE(sat)} = 1.8 \text{ V}$	$V_{CE(sat)} = 1.8 \text{ V}$

**Part name** (Marking on product)

MIXA10WB1200TML



E72873

Pin configuration see outlines.

### Features:

- High level of integration - only one power semiconductor module required for the whole drive
- Rugged XPT design (Xtreme light Punch Through) results in:
  - short circuit rated for 10  $\mu\text{sec}$ .
  - very low gate charge
  - square RBSOA @ 3x  $I_c$
  - low EMI
- Thin wafer technology combined with the XPT design results in a competitive low  $V_{CE(sat)}$
- Temperature sense included
- SONIC™ diode
  - fast and soft reverse recovery
  - low operating forward voltage

### Application:

- AC motor drives
- Pumps, Fans
- Washing machines
- Air-conditioning system
- Inverter and power supplies

### Package:

- DCB based "E1-Pack"
- Assembly height is 17 mm
- Insulated base plate
- UL registered E72873

## Output Inverter T1 - T6

## Ratings

Symbol	Definitions	Conditions	min.	typ.	max.	Unit
$V_{CES}$	collector emitter voltage	$T_{VJ} = 25^\circ\text{C}$		1200		V
$V_{GES}$	max. DC gate voltage	continuous		$\pm 20$		V
$V_{GEM}$	max. transient collector gate voltage	transient		$\pm 30$		V
$I_{C25}$	collector current	$T_C = 25^\circ\text{C}$	17		A	
$I_{C80}$		$T_C = 80^\circ\text{C}$	12		A	
$P_{tot}$	total power dissipation	$T_C = 25^\circ\text{C}$	63		W	
$V_{CE(sat)}$	collector emitter saturation voltage	$I_C = 9 \text{ A}; V_{GE} = 15 \text{ V}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	1.8 2.1	2.1	V
$V_{GE(th)}$	gate emitter threshold voltage	$I_C = 0.3 \text{ mA}; V_{GE} = V_{CE}$	$T_{VJ} = 25^\circ\text{C}$	5.5	6.0	V
$I_{CES}$	collector emitter leakage current	$V_{CE} = V_{CES}; V_{GE} = 0 \text{ V}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	0.02 0.2	0.1	mA mA
$I_{GES}$	gate emitter leakage current	$V_{GE} = \pm 20 \text{ V}$		500		nA
$Q_{G(on)}$	total gate charge	$V_{CE} = 600 \text{ V}; V_{GE} = 15 \text{ V}; I_C = 10 \text{ A}$		27		nC
$t_{d(on)}$	turn-on delay time	$T_{VJ} = 125^\circ\text{C}$ $V_{CE} = 600 \text{ V}; I_C = 10 \text{ A}$ $V_{GE} = \pm 15 \text{ V}; R_G = 100 \Omega$	70			ns
$t_r$	current rise time		40			ns
$t_{d(off)}$	turn-off delay time		250			ns
$t_f$	current fall time		100			ns
$E_{on}$	turn-on energy per pulse		1.1			mJ
$E_{off}$	turn-off energy per pulse		1.1			mJ
<b>RBSOA</b>	reverse bias safe operating area	$V_{GE} = \pm 15 \text{ V}; R_G = 100 \Omega; V_{CEK} = 1200 \text{ V}$ $T_{VJ} = 125^\circ\text{C}$		30		A
<b>I<sub>sc</sub> (SCSOA)</b>	short circuit safe operating area	$V_{CE} = 900 \text{ V}; V_{GE} = \pm 15 \text{ V};$ $R_G = 100 \Omega; t_p = 10 \mu\text{s}; \text{non-repetitive}$	$T_{VJ} = 125^\circ\text{C}$	40		A
$R_{thJC}$ $R_{thCH}$	thermal resistance junction to case thermal resistance case to heatsink	(per IGBT)		0.7	2.0	K/W K/W

## Output Inverter D1 - D6

## Ratings

Symbol	Definitions	Conditions	min.	typ.	max.	Unit
$V_{RRM}$	max. repetitive reverse voltage	$T_{VJ} = 25^\circ\text{C}$		1200		V
$I_{F25}$	forward current	$T_C = 25^\circ\text{C}$	19		A	
$I_{F80}$		$T_C = 80^\circ\text{C}$	13		A	
$V_F$	forward voltage	$I_F = 10 \text{ A}; V_{GE} = 0 \text{ V}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	1.95 1.85	2.2	V V
$Q_{rr}$	reverse recovery charge	$T_{VJ} = 125^\circ\text{C}$ $V_R = 600 \text{ V}$ $di_F/dt = -250 \text{ A}/\mu\text{s}$ $I_F = 10 \text{ A}; V_{GE} = 0 \text{ V}$	tbd			$\mu\text{C}$
$I_{RM}$	max. reverse recovery current		tbd			A
$t_{rr}$	reverse recovery time		tbd			ns
$E_{rec}$	reverse recovery energy		tbd			mJ
$R_{thJC}$ $R_{thCH}$	thermal resistance junction to case thermal resistance case to heatsink	(per diode)		2.4 0.8	K/W K/W	

## Brake T7

## Ratings

Symbol	Definitions	Conditions	min.	typ.	max.	Unit
$V_{CES}$	collector emitter voltage	$T_{VJ} = 25^\circ C$		1200		V
$V_{GES}$	max. DC gate voltage	continuous		$\pm 20$		V
$V_{GEM}$	max. transient collector gate voltage	transient		$\pm 30$		V
$I_{C25}$	collector current	$T_C = 25^\circ C$	17		A	
$I_{C80}$		$T_C = 80^\circ C$	12		A	
$P_{tot}$	total power dissipation	$T_C = 25^\circ C$	63		W	
$V_{CE(sat)}$	collector emitter saturation voltage	$I_C = 9 A; V_{GE} = 15 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	1.8 2.1	2.1	V
$V_{GE(th)}$	gate emitter threshold voltage	$I_C = 0.3 mA; V_{GE} = V_{CE}$	$T_{VJ} = 25^\circ C$	5.5	6.0	V
$I_{CES}$	collector emitter leakage current	$V_{CE} = V_{CES}; V_{GE} = 0 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	0.01 0.1	0.1	mA mA
$I_{GES}$	gate emitter leakage current	$V_{GE} = \pm 20 V$		500		nA
$Q_{G(on)}$	total gate charge	$V_{CE} = 600 V; V_{GE} = 15 V; I_C = 10 A$		27		nC
$t_{d(on)}$	turn-on delay time	<div style="border-left: 1px solid black; padding-left: 10px;">inductive load <math>V_{CE} = 600 V; I_C = 10 A</math> <math>V_{GE} = \pm 15 V; R_G = 100 \Omega</math></div>	70			ns
$t_r$	current rise time		40			ns
$t_{d(off)}$	turn-off delay time		250			ns
$t_f$	current fall time		100			ns
$E_{on}$	turn-on energy per pulse		1.1			mJ
$E_{off}$	turn-off energy per pulse		1.1			mJ
<b>RBSOA</b>	reverse bias safe operating area	$V_{GE} = \pm 15 V; R_G = 100 \Omega; V_{CEK} = 1200 V$ $T_{VJ} = 125^\circ C$		30		A
<b>I<sub>sc</sub> (SCSOA)</b>	short circuit safe operating area	$V_{CE} = 900 V; V_{GE} = \pm 15 V;$ $R_G = 100 \Omega; t_p = 10 \mu s$ ; non-repetitive	$T_{VJ} = 125^\circ C$	40		A
$R_{thJC}$ $R_{thCH}$	thermal resistance junction to case thermal resistance case to heatsink	(per IGBT)		0.7	2.0 K/W K/W	

## Brake Chopper D7

## Ratings

Symbol	Definitions	Conditions	min.	typ.	max.	Unit
$V_{RRM}$	max. repetitive reverse voltage	$T_{VJ} = 150^\circ C$		1200		V
$I_{F25}$	forward current	$T_C = 25^\circ C$		19		A
$I_{F80}$		$T_C = 80^\circ C$		13		A
$V_F$	forward voltage	$I_F = 10 A; V_{GE} = 0 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	1.95 1.85	2.2	V V
$I_R$	reverse current	$V_R = V_{RRM}$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	0.01 0.1	0.1	mA mA
$Q_{rr}$ $I_{RM}$ $t_{rr}$ $E_{rec}$	reverse recovery charge max. reverse recovery current reverse recovery time reverse recovery energy	$V_R = 600 V$ $di_F/dt = tbd A/\mu s$ $I_F = 10 A; V_{GE} = 0 V$	$T_{VJ} = 125^\circ C$	tbd tbd tbd tbd		$\mu C$ A ns mJ
$R_{thJC}$ $R_{thCH}$	thermal resistance junction to case thermal resistance case to heatsink	(per diode)		0.8	2.4 K/W K/W	

**Input Rectifier Bridge D8 - D11**

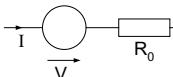
<b>Ratings</b>						
<b>Symbol</b>	<b>Definitions</b>	<b>Conditions</b>	<b>min.</b>	<b>typ.</b>	<b>max.</b>	<b>Unit</b>
$V_{RRM}$	max. repetitive reverse voltage		$T_{VJ} = 25^\circ\text{C}$		1600	V
$I_{FAV}$	average forward current	sine 180°	$T_C = 80^\circ\text{C}$		24	A
$I_{DAVM}$	max. average DC output current	rect.; $d = 1/3$	$T_C = 80^\circ\text{C}$		69	A
$I_{FSM}$	max. forward surge current	$t = 10 \text{ ms}; \text{sine } 50 \text{ Hz}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$		270 240	A
$I^2t$	$I^2t$ value for fusing	$t = 10 \text{ ms}; \text{sine } 50 \text{ Hz}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$		360 290	$\text{A}^2\text{s}$ $\text{A}^2\text{s}$
$P_{tot}$	total power dissipation		$T_C = 25^\circ\text{C}$		70	W
$V_F$	forward voltage	$I_F = 30 \text{ A}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	1.27 1.24	1.7	V
$I_R$	reverse current	$V_R = V_{RRM}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	0.02 0.2	mA mA	
$R_{thJC}$	thermal resistance junction to case	(per diode)			1.8	K/W
$R_{thCH}$	thermal resistance case to heatsink	(per diode)			0.6	K/W

**Temperature Sensor NTC**

<b>Ratings</b>						
<b>Symbol</b>	<b>Definitions</b>	<b>Conditions</b>	<b>min.</b>	<b>typ.</b>	<b>max.</b>	<b>Unit</b>
$R_{25}$	resistance		$T_C = 25^\circ\text{C}$	4.45	4.7	kΩ
$B_{25/50}$					3510	K

**Module**

<b>Ratings</b>						
<b>Symbol</b>	<b>Definitions</b>	<b>Conditions</b>	<b>min.</b>	<b>typ.</b>	<b>max.</b>	<b>Unit</b>
$T_{VJ}$	operating temperature		-40		125	°C
$T_{VJM}$	max. virtual junction temperature				150	°C
$T_{stg}$	storage temperature		-40		125	°C
$V_{ISOL}$	isolation voltage	$I_{ISOL} \leq 1 \text{ mA}; 50/60 \text{ Hz}$			2500	V~
<b>CTI</b>	comparative tracking index				-	
$M_d$	mounting torque	(M4)	2.0		2.2	Nm
$d_s$	creep distance on surface		12.7			mm
$d_A$	strike distance through air		7.6			mm
<b>Weight</b>				40		g

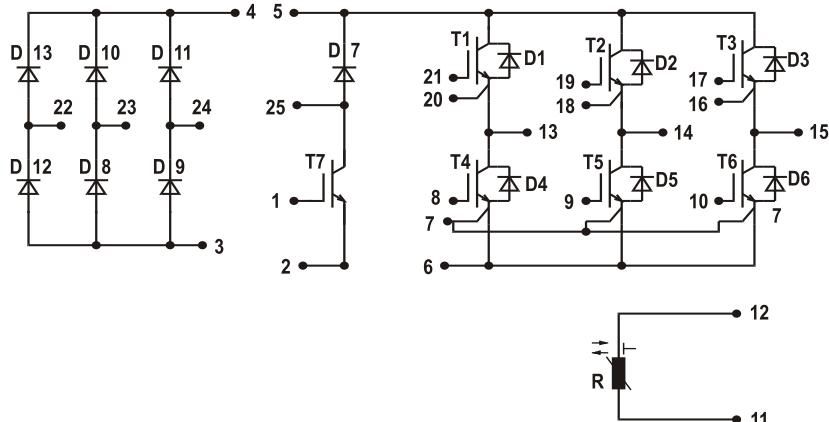
**Equivalent Circuits for Simulation**

<b>Ratings</b>						
<b>Symbol</b>	<b>Definitions</b>	<b>Conditions</b>	<b>min.</b>	<b>typ.</b>	<b>max.</b>	<b>Unit</b>
$V_0$	rectifier diode	D8 - D13	$T_{VJ} = 150^\circ\text{C}$		0.86	V
$R_0$					12.3	mΩ
$V_0$	IGBT	T1 - T6	$T_{VJ} = 150^\circ\text{C}$		1.1	V
$R_0$					153	mΩ
$V_0$	free wheeling diode	D1 - D6	$T_{VJ} = 150^\circ\text{C}$		1.09	V
$R_0$					91	mΩ
$V_0$	IGBT	T7	$T_{VJ} = 150^\circ\text{C}$		1.1	V
$R_0$					153	mΩ
$V_0$	free wheeling diode	D7	$T_{VJ} = 150^\circ\text{C}$		1.09	V
$R_0$					91	mΩ

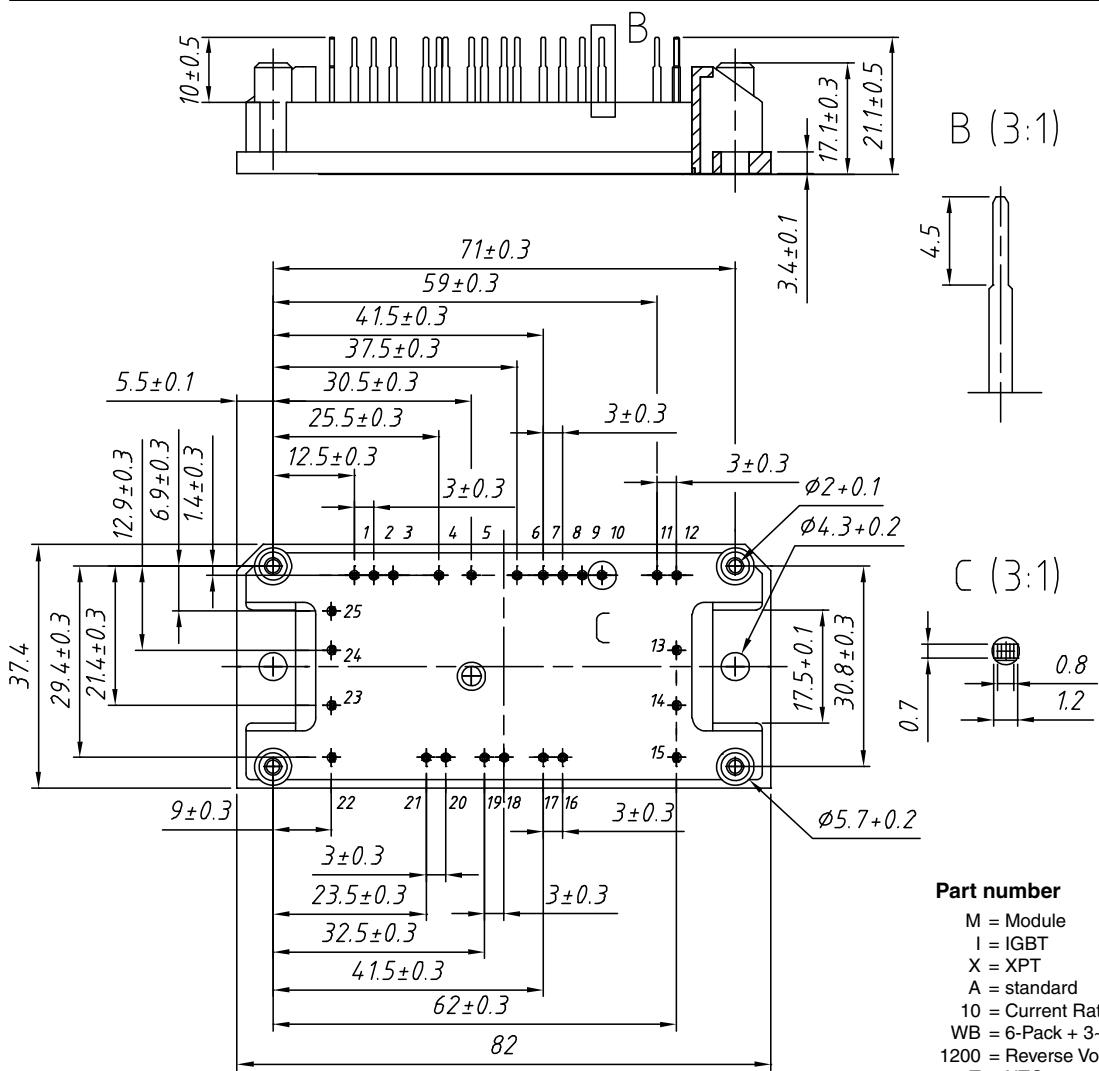
IXYS reserves the right to change limits, test conditions and dimensions.

 $T_C = 25^\circ\text{C}$  unless otherwise stated

20110916c

**Circuit Diagram****Outline Drawing**

Dimensions in mm (1 mm = 0.0394")

**Part number**

M = Module  
 I = IGBT  
 X = XPT  
 A = standard  
 10 = Current Rating [A]  
 WB = 6-Pack + 3~ Rectifier Bridge & Brake Unit  
 1200 = Reverse Voltage [V]  
 T = NTC  
 ML = E1-Pack

Ordering	Part Name	Marking on Product	Delivering Mode	Base Qty	Ordering Code
Standard	MIXA 10 WB 1200 TML	MIXA10WB1200TML	Box	10	509367

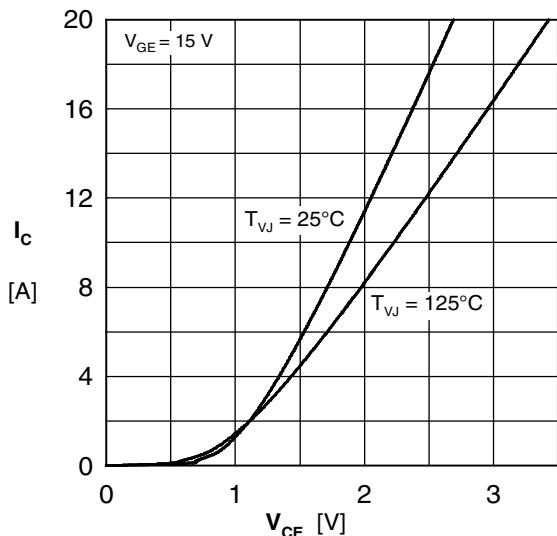


Fig. 1 Typ. output characteristics

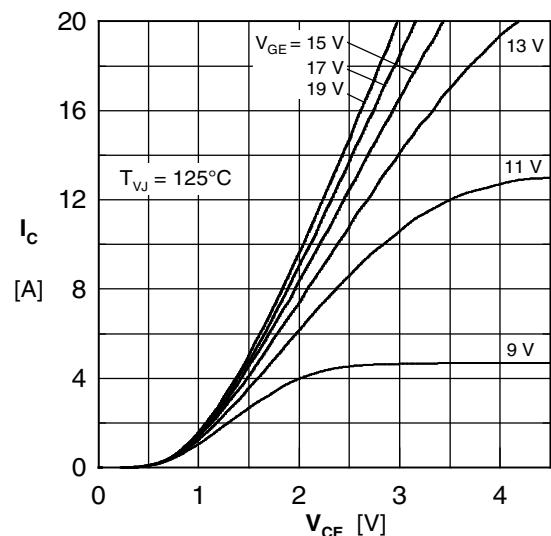


Fig. 2 Typ. output characteristics

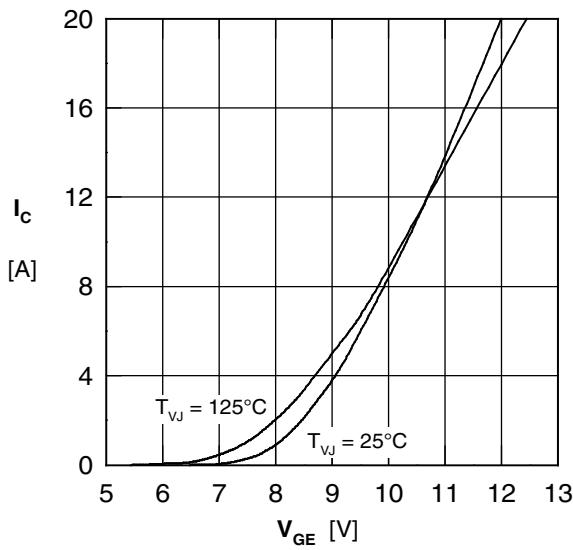


Fig. 3 Typ. transfer characteristics

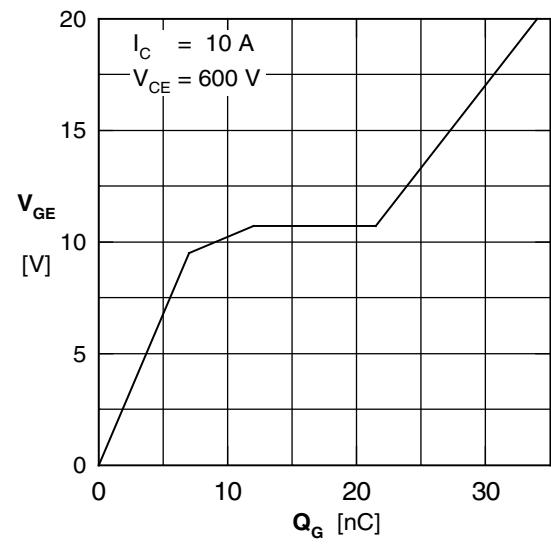


Fig. 4 Typ. turn-on gate charge

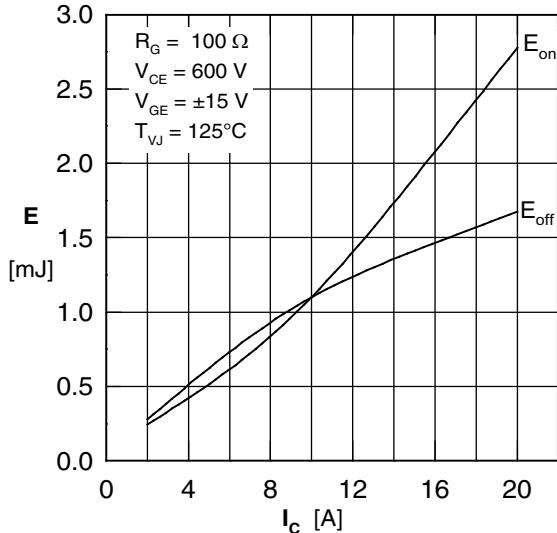


Fig. 5 Typ. switching energy vs. collector current

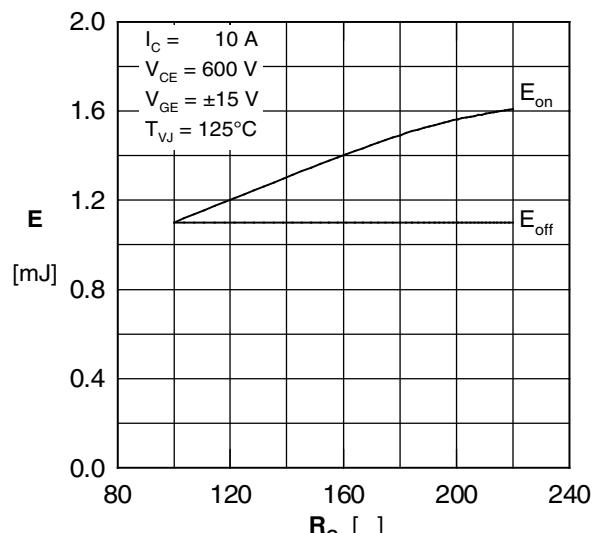


Fig. 6 Typ. switching energy vs. gate resistance

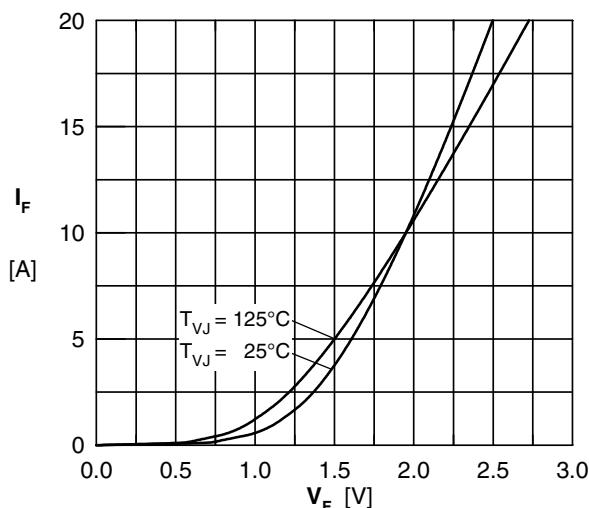


Fig. 7 Typ. forward characteristics

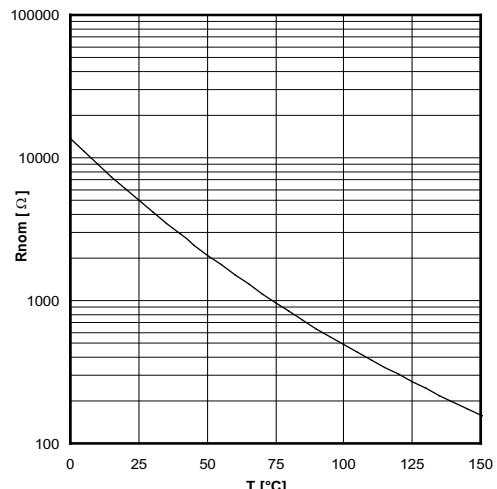


Fig. 8 Typ. thermistor resistance vs. temperature

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[FD401R17KF6C\\_B2](#) [FD-DF80R12W1H3\\_B52](#) [FF200R06YE3](#) [FF300R12KE4\\_E](#) [FF450R12ME4P](#) [FF600R12IP4V](#) [FP10R06W1E3\\_B11](#)  
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[F475R07W1H3B11ABOMA1](#) [FD1400R12IP4D](#) [FD200R12PT4\\_B6](#) [FD800R33KF2C-K](#) [FF1200R17KP4\\_B2](#) [FF300R17KE3\\_S4](#)  
[FF300R17ME4\\_B11](#) [FF401R17KF6C\\_B2](#) [FF650R17IE4D\\_B2](#) [FF900R12IP4D](#) [FF900R12IP4DV](#) [STGIF7CH60TS-L](#) [FP50R07N2E4\\_B11](#)  
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